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Specification for Approval

Customer:	
Model Name:	

Sı	Customer approval		
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		



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Revision Record

REV NO.	REV DATE	CONTENTS	Note
А	2012-11-15	NEW ISSUE	

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1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution

2. General Information

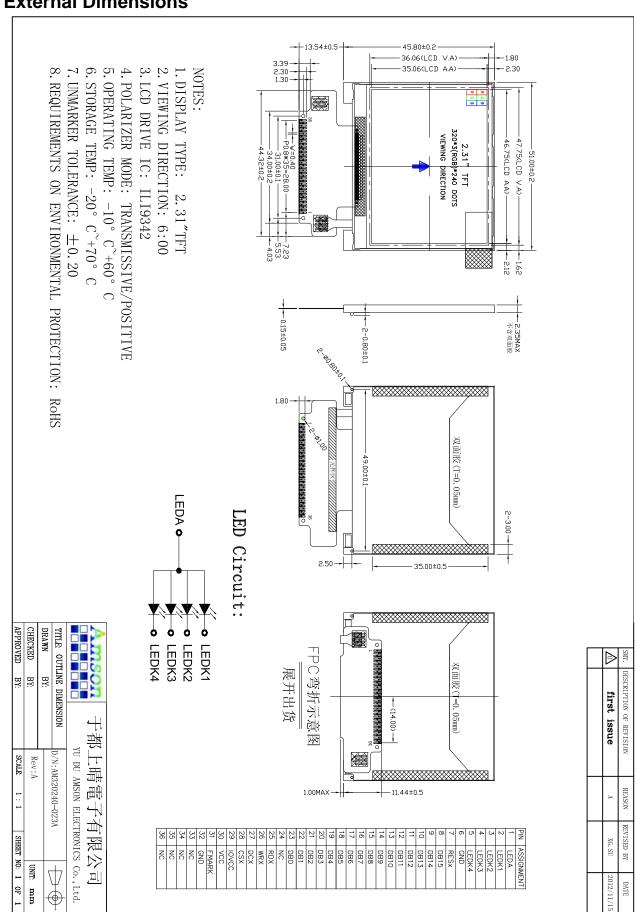
ITEM	STANDARD VALUES	UNITS
LCD type	2.31"TFT	
Dot arrangement	320(RGB)×240	dots
Color filter array	RGB vertical stripe	
Display mode	TN / Transmission / Normally White	
Viewing Direction	6 o'clock(Gray scale inversion)	
Driver IC	ILI9342C	
Module size	51.0(W)×45.8(H)×2.35(T)	mm
Active area	46.752(W)×35.064(H)	mm
Dot pitch	0.1461(W)×0.1461(H)	mm
Interface	i80-system 8/16 bit MCU interface	
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	4 White LED In Parallel	
Weight	TBD	g



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3. External Dimensions





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4. Interface Description

PIN NO. PIN NAME 1 LEDA Power supply for backlight anode input terminal. 2 LEDK1 Power supply for backlight cathode input terminals. 3 LEDK2 Power supply for backlight cathode input terminals. 4 LEDK3 Power supply for backlight cathode input terminals. 5 LEDK4 Power supply for backlight cathode input terminals. 6 GND System power ground 7 RESX Reset signal input terminal, active at 'L'. 8 DB15 9 DB14 10 DB13 11 DB12 12 DB11 13 DB10 14 DB9 15 DB8 16 DB7 17 DB6 18 DB5 19 DB4 20 DB3 21 DB2 22 DB1 23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. Register select signal input terminal, Active at 'L'. Register select signal input terminal: CX='H': select a control register; DCX='H': select a ontrol register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 31 FMARK 32 GND System power ground 33 NC 34 NC 35 NC 36 NC		tace Desc	ription
2 LEDK1 Power supply for backlight cathode input terminals. 3 LEDK2 Power supply for backlight cathode input terminals. 4 LEDK3 Power supply for backlight cathode input terminals. 5 LEDK4 Power supply for backlight cathode input terminals. 6 GND System power ground 7 RESX Reset signal input terminal, active at 'L'. 8 DB15 PO DB14 PO DB13 PO DB14 PO DB13 PO DB14 PO DB13 PO DB14 PO DB14 PO DB15 PO DB16 P	PIN NO.	PIN NAME	DESCRIPTION
LEDK2	1	LEDA	Power supply for backlight anode input terminal.
4 LEDK3 Power supply for backlight cathode input terminals. 5 LEDK4 Power supply for backlight cathode input terminals. 6 GND System power ground 7 RESX Reset signal input terminal, active at 'L'. 8 DB15 9 DB14 10 DB13 11 DB12 12 DB11 13 DB10 14 DB9 15 DB8 16 DB7 17 DB6 18 DB5 19 DB4 20 DB3 21 DB2 22 DB1 23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 8 Register select signal input terminal: DCX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground No Connection	2	LEDK1	Power supply for backlight cathode input terminals.
5 LEDK4 Power supply for backlight cathode input terminals. 6 GND System power ground 7 RESX Reset signal input terminal, active at 'L'. 8 DB15 9 DB14 10 DB13 11 DB12 12 DB11 13 DB10 14 DB9 15 DB8 16 DB7 17 DB6 18 DB5 19 DB4 20 DB3 21 DB2 22 DB1 23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. 27 DCX Write signal input terminal. Active at 'L'. 28 CSX Chip select a control register; DCX='L': select a control register; DCX='L': select an index or status register. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC	3	LEDK2	Power supply for backlight cathode input terminals.
RESX	4	LEDK3	Power supply for backlight cathode input terminals.
7 RESX Reset signal input terminal, active at 'L'. 8 DB15 9 DB14 10 DB13 11 DB12 12 DB11 13 DB10 14 DB9 15 DB8 16 DB7 17 DB6 18 DB5 19 DB4 20 DB3 21 DB2 22 DB1 23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. 27 DCX CX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Analog Supply Voltage (1.8V/2.8V). 30 VCC <td< td=""><td>5</td><td>LEDK4</td><td>Power supply for backlight cathode input terminals.</td></td<>	5	LEDK4	Power supply for backlight cathode input terminals.
B	6	GND	System power ground
9 DB14 10 DB13 11 DB12 12 DB11 13 DB10 14 DB9 15 DB8 16 DB7 17 DB6 18 DB5 19 DB4 20 DB3 21 DB2 22 DB1 23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. 27 DCX Register select signal input terminal:	7	RESX	Reset signal input terminal, active at 'L'.
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17 DB6 18 DB5 19 DB4 20 DB3 21 DB2 22 DB1 23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. Register select signal input terminal: DCX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC	16	DB7	
19 DB4 20 DB3 21 DB2 22 DB1 23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. 27 DCX Register select signal input terminal: DCX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground No Connection	17	DB6	
20 DB3 21 DB2 22 DB1 23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. 27 DCX Register select signal input terminal: 28 DCX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC	18	DB5	
21 DB2 22 DB1 23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. 27 DCX Register select signal input terminal: DCX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC	19	DB4	
22 DB1 23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. 27 DCX Register select signal input terminal: 28 DCX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC	20	DB3	
23 DB0 24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. 27 DCX Register select signal input terminal: DCX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC	21	DB2	
24 NC No Connection 25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. 27 PCX Register select signal input terminal: 28 DCX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC No Connection	22	DB1	
25 RDX Read signal input terminal, Active at 'L'. 26 WRX Write signal input terminal, Active at 'L'. 27 DCX Register select signal input terminal: 28 DCX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC No Connection	23	DB0	
26 WRX Write signal input terminal, Active at 'L'. Register select signal input terminal: DCX='H': select a control register; DCX='L': select an index or status register. 28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC No Connection	24	NC	No Connection
PCX Register select signal input terminal: DCX='H': select a control register; DCX='L': select an index or status register. Chip select signal input terminal, Active at 'L'. PCX='L': select an index or status register. Chip select signal input terminal, Active at 'L'. PCX='L': select an index or status register. Chip select signal input terminal, Active at 'L'. PCX='L': select a control register; DCX='L': select an index or status register. Chip select signal input terminal: CHIP SELECT	25	RDX	Read signal input terminal, Active at 'L'.
DCX='H': select a control register; DCX='L': select an index or status register. Chip select signal input terminal, Active at 'L'. DCX='L': select an index or status register. Chip select signal input terminal, Active at 'L'. DCX='L': select a control register; DCX='L': select a control register. 28	26	WRX	Write signal input terminal, Active at 'L'.
DCX='L': select an index or status register. 28	27	DCV	
28 CSX Chip select signal input terminal, Active at 'L'. 29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC No Connection	21	DCX	
29 IOVCC Logic Supply Voltage (1.8V/2.8V). 30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC	28	CSX	
30 VCC Analog Supply Voltage (2.8V). 31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC No Connection			
31 FMARK Tearing effect output pin to synchronize MPU to frame writing. 32 GND System power ground 33 NC 34 NC 35 NC			
32 GND System power ground 33 NC 34 NC 35 NC No Connection			
33 NC 34 NC 35 NC No Connection			
34 NC No Connection			
35 NC No Connection			No Compostion
36 NC	35		NO Connection
	36	NC	



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5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	3.3	V
Analog Supply Voltage	VCC	-0.3	3.6	V
Input Voltage	Vin	-0.3	IOVCC+0.3	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

6. DC Characteristics

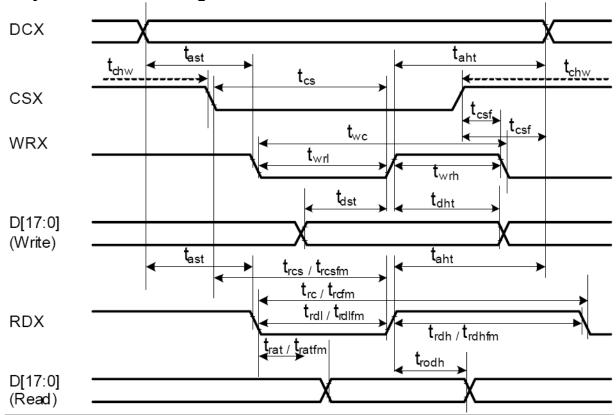
Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8/2.8	3.3	V	-
Analog Supply Voltage	VCC	2.6	2.8	3.3	٧	
Input High Voltage	V _{IH}	0.8IOVCC		IOVCC	٧	Digital input pins
Input Low Voltage	V _{IL}	GND		0.2IOVCC	٧	Digital input pins
Output High Voltage	V _{OH}	0.8IOVCC	-	IOVCC	٧	Digital output pins
Output Low Voltage	V _{OL}	GND	-	0.2IOVCC	V	Digital output pins
I/O Leak Current	ILI	-1		1	uA	

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7. Timing Characteristics

7.1 i80-System Interface Timing Characteristics

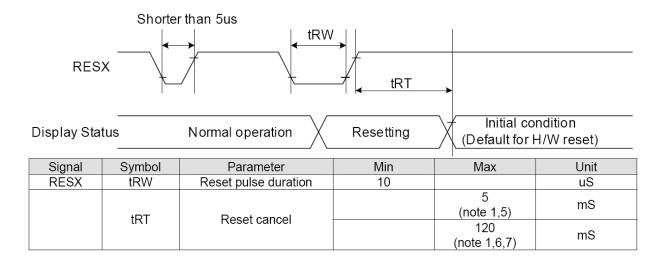


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	t _{ast}	Address setup time	0	-	ns	
DCX	t _{hat}	Address hold time (Write/Read)	10	-	ns	
	t _{chw}	CSX "H" pulse width	0	-	ns	
	t _{cs}	Chip Select setup time (Write)	15	-	ns	
CSX	t _{rcs}	Chip Select setup time (Read ID)	45	-	ns	
	t _{rcsfm}	Chip Select setup time (Read FM)	355	-	ns	
	t _{csf}	Chip Select Wait time (Write/Read)	10	-	ns	
	t _{wc}	Write cycle	66		ns	
WRX	t _{wrh}	Write Control pulse H duration	33	-	ns	
	t _{wrl}	Write Control pulse L duration	33	-	ns	
	t _{rc}	Read cycle (ID)	160	-	ns	
RDX (ID)	t _{rdh}	Read Control pulse H duration	90	-	ns	When read ID data
	t _{rdl}	Read Control pulse L duration	45	-	ns	
	t _{rcfm}	Read Cycle (FM)	450	-	ns	When read from the frame
RDX (FM)	t _{rdhfm}	Read Control H duration (FM)	90	-	ns	
	t _{rdlfm}	Read Control L duration (FM)	355	-	ns	memory
DD[47.0]	t _{dst}	Write data setup time	10	-	ns	
DB[17:0],	t _{dht}	Write data hold time	10	-	ns	For maximum CL =20nF
DB[15:0], DB[8:0],	t _{rat}	Read access time	-	40	ns	For maximum CL=30pF For minimum CL=8pF
DB[8:0], DB[7:0]	t _{ratfm}	Read access time	-	50	ns	1 Of Hillimidill CL-8pF
00[7.0]	t _{rod}	Read output disable time	45	50	ns	

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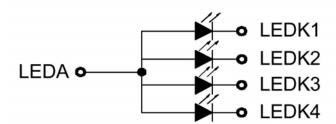
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7.2 Reset Timing Characteristics



8. Backlight Characteristics

LED Circuit:



Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	3.0	3.2	3.5	V	If=60mA
Supply Current	If		60	80	mA	
Luminous Intensity for LCM		200	230		Cd/m ²	If=60mA
Uniformity for LCM		80			%	If=60mA
Life Time		20000			Hr	If=60mA
Backlight Color		\	If=60mA			

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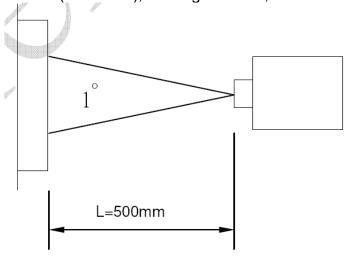
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9. Optical Characteristics

Item		Symbol	Condition	Min.	Тур.	Max.	Unit	Remark
Transmitta	ance	T		6.0	6.3		%	
Contrast F	Ratio	CR		400	500			Note3
Response	Time	Tr+Tf	25°C		20	30	ms	Note4
	3H	θ3H(R)		60	70			
Viewing	9H	θ9H(L)	CR≥10	60	70			Note5
Angle	6H	φ6H(D)	CR210	50	60			Notes
	12H	φ12(U)		60	70			
		Х		0.255	0.305	0.355		
	White	у	θ=φ=0°	0.311	0.361	0.411	-	
		λ		I			-	
		Х	θ=φ=0°	0.571	0.621	0.671		
	Red	у		0.269	0.319	0.369		
Color Filton		λ		I			-	
Color Filter Chromaticity		Х		0.252	0.302	0.352		Note6
Officialities	Green	у	θ=φ=0°	0.515	0.565	0.615	-	
		λ		I			-	
		Х		0.087	0.137	0.187		
	Blue	у	θ=φ=0°	0.114	0.164	0.214		
		λ						
	NTSC			45 %	50 %			

Note1.Ambient condition: 25°C±2°C, 60±10%RH, under 10 Lux in the darkroom.

Note2.Measure device: BM-5A (TOPCON), viewing cone=1°, IL=20mA.

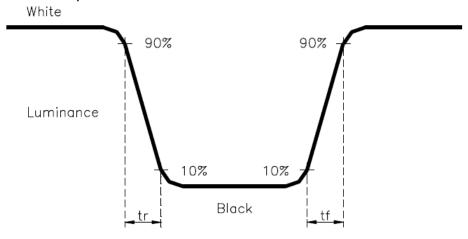


Note3. Definition of Contrast Ratio:

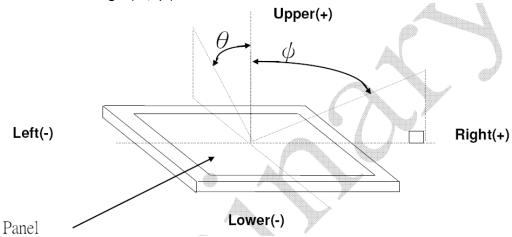
CR = White Luminance (ON) / Black Luminance (OFF)

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Note4. Definition of response time: The response time is defined as the time interval between the 10% and 90% amplitudes.



Note5. Definition of view angle(θ , ϕ):



Note6. Light source: C light.



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10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
	High Temperature Storage	80°C±2°C×200Hours	
	Low Temperature Storage	-30°C±2°C×200Hours	
	High Temperature Operating	70°C±2°C×120Hours	Inspection after 2~4hours
	Low Temperature Operating	-20°C±2°C×120Hours	storage at room temperature, the samples should be free from
	Temperature Cycle(Storage)	-20°C \Longrightarrow 25°C \Longrightarrow 70°C (30min) (30min) 1cycle Total 10cycle	defects: 1, Air bubble in the LCD. 2, Seal leak. 3, Non-display. 4, Missing segments.
	Damp Proof Test (Storage)	50°C±5°C×90%RH×120Hours	5, Glass crack. 6, Current IDD is twice higher than initial value.
	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5M X,Y,Z direction for total 3hours (Packing Condition)	7, The surface shall be free from damage. 8, The electric characteristic requirements shall be
	Drooping Test	Drop to the ground from 1M height one time every side of carton. (Packing Condition)	satisfied.
	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

REMARK:

- 1, The Test samples should be applied to only one test item.
- 2, Sample side for each test item is 5~10pcs.
- 3,For Damp Proof Test, Pure water(Resistance > 10M Ω)should be used.
- 4,In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- 5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



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11. Inspection Standard

This standard apply to C-STN/TFT module

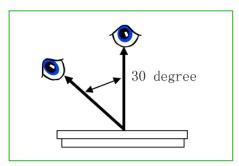
1. Spot check plan:

According to spot check level ${\rm II}$,MIL-STD-105D Level ${\rm II}$,the rank of accept or reject is below:

3A、2A: major non-conformance: AQL 0.25 minor non-conformance: AQL 0.4

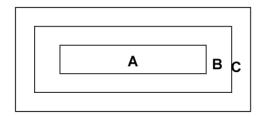
1A: major non-conformance: AQL 0.65 minor non-conformance: AQL 1.

2. Inspection condition:



Under daylight lamp 20 \sim 40W, product distance inspector 'eye 30cm,incline degree 30° $_{\circ}$

3. LCD area define:



Area A: display area

Area B: VA area

Area C: out of VA area, not in sight after assembly

Remark: non-conformance at area C, but is OK that isn't influence reliability of product & assembly by customer.



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4. Inspection standard

4.1 Major non-conformance

NO.	Item Inspection standard		Rate
4.1.1	Function non-conformance	 No display, display abnormally Miss line, short B/L no function or function abnormally TP no function 	major
4.1.2	miss	No matter miss what component	
4.1.3	Out of size	Module dimension out of spec	

4.2 Appearance non-conformance

NO.	Item	Inspection standard							Rate
4.2.1	Black or white spot (power on)	dot non-conformance define Φ $\Phi = \frac{+y}{2} x ($							
		A grade Most approve q'ty							
		area size (mm)		A			С		
		Ф≤0.10		ignore				Minor	
		0.10<Φ≤0.15		4					
		0.15<Φ≤0.20		2		ignore			
		0.20<Φ≤0.25		1					
		0.25<Ф		0					
		Most approve 4 damages, dot to dot ≥10mm							
4.2.2	Black or white line (power on)	A grade Size(mm) Most approve q'ty							
		L(length)	W(width)		Α		В	C	
		ignore	W≤0.03		ignore				
		L≤5.0	0.03< W≤0.05		3			ignore	Minor
		L≤3.0	0.05< W≤0.07		2				
			0.07 <w< td=""><td colspan="2">Treat with dot non-conformance</td><td></td><td></td></w<>		Treat with dot non-conformance				
		Most approve 3 damages, line to line ≥10mm							



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4.2.3	Polarizer position				sallow out of LC area (special	
4.2.4	LCD non-conform ance	(iii) com	X ≤3.0 Crash disall monly surface X ≤2.0	Y <frame edge<="" th=""/> <th>Z ignore</th> <th>Minor</th>	Z ignore	Minor
4.2.5	Contrast voltage warp	VOP/VIcd voltage of confirmed sample \pm 0.15V				
4.2.6	color	Color & luminance of module scope reference spec				
4.2.7	Cross talk	Reference confirmed limit sample				



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12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI), Sulfur (S)

If goods were sent without being sili8con coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to VCC or GND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.



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Usage under the maximum operating temperature, 50%Rh or less is required.

12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT, and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

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14. Packing Method

